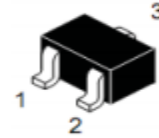
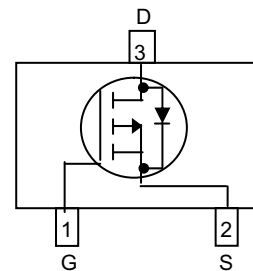


WPM6205
Single P-Channel, -20V, -4.8A, Power MOSFET
[Http://www.sh-willsemi.com](http://www.sh-willsemi.com)

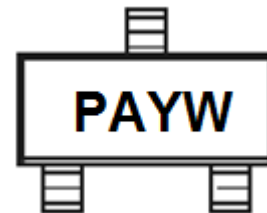
V_{DS} (V)	Typical $R_{DS(on)}$ (m Ω)
-20	33@ $V_{GS}=-4.5V$
	44@ $V_{GS}=-2.5V$
	65@ $V_{GS}=-1.8V$


SOT-23-3L

Descriptions

The WPM6205 is P-Channel enhancement MOS Field Effect Transistor. Uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit. Standard Product WPM6205 is Pb-free.

Pin configuration (Top view)
Features

- Trench Technology
- Supper high density cell design
- Excellent ON resistance
- Extremely Low Threshold Voltage
- Small package SOT-23-3L



PA = Device Code
 Y = Year
 W = Week(A~z)

Applications

- DC/DC converters
- Power supply converters circuit
- Load/Power Switching for portable device

Marking
Order information

Device	Package	Shipping
WPM6205-3/TR	SOT-23-3L	3000/Tape&Reel

Absolute Maximum ratings

Parameter	Symbol	10 s	Steady State	Unit	
Drain-Source Voltage	V_{DS}	-20		V	
Gate-Source Voltage	V_{GS}	± 12			
Continuous Drain Current ^{a d}	I_D	$T_A=25^\circ\text{C}$	-4.8	-4.1	A
		$T_A=70^\circ\text{C}$	-3.8	-3.3	
Maximum Power Dissipation ^{a d}	P_D	$T_A=25^\circ\text{C}$	1.5	1.1	W
		$T_A=70^\circ\text{C}$	0.9	0.7	
Continuous Drain Current ^{b d}	I_D	$T_A=25^\circ\text{C}$	-4.2	-3.8	A
		$T_A=70^\circ\text{C}$	-3.4	-3.0	
Maximum Power Dissipation ^{b d}	P_D	$T_A=25^\circ\text{C}$	1.1	0.9	W
		$T_A=70^\circ\text{C}$	0.7	0.6	
Pulsed Drain Current ^c	I_{DM}	-20		A	
Operating Junction Temperature	T_J	-55 to 150		$^\circ\text{C}$	
Lead Temperature	T_L	260		$^\circ\text{C}$	
Storage Temperature Range	T_{stg}	-55 to 150		$^\circ\text{C}$	

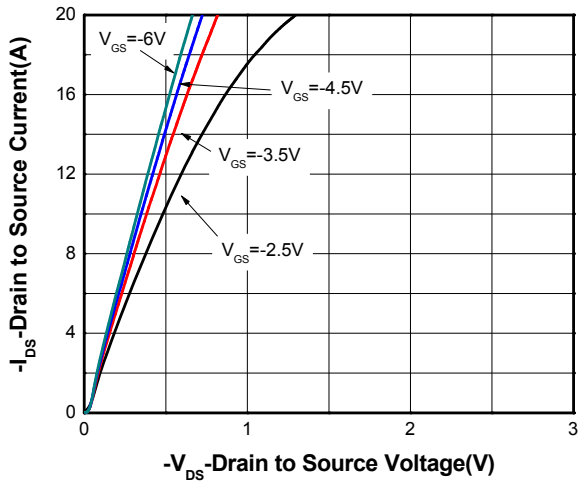
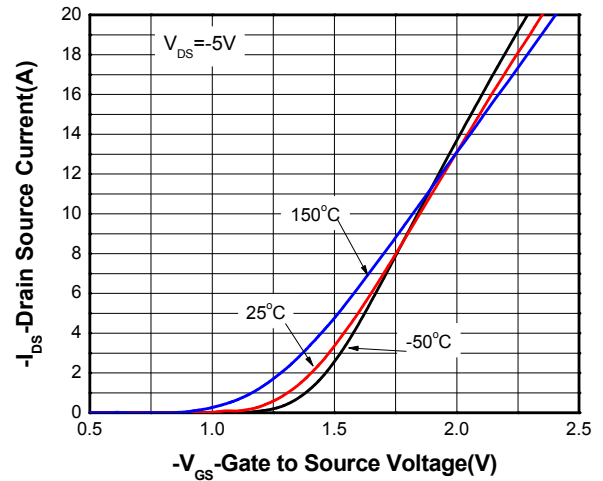
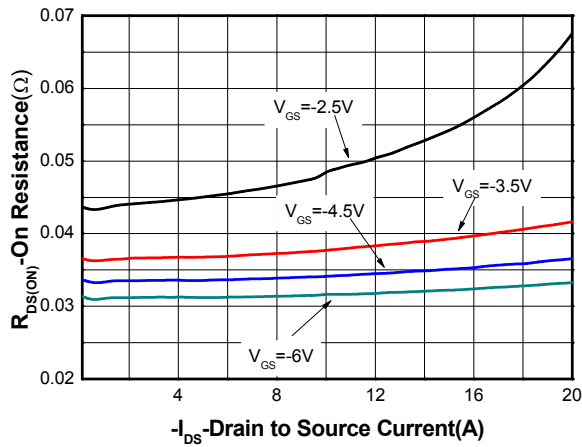
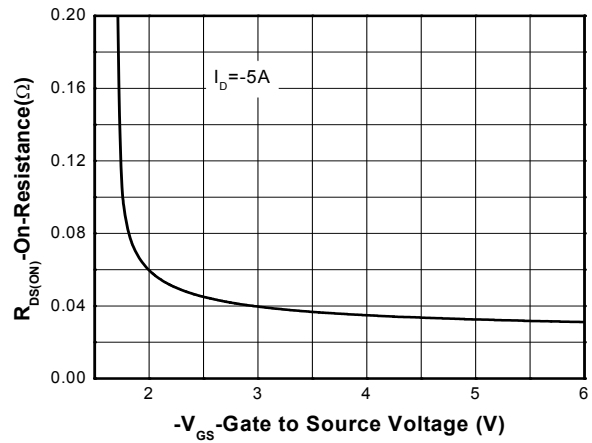
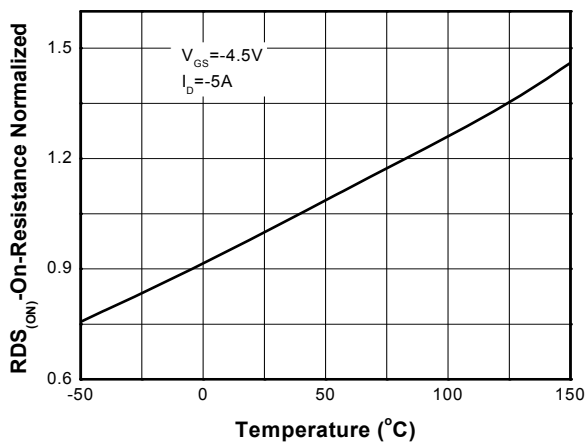
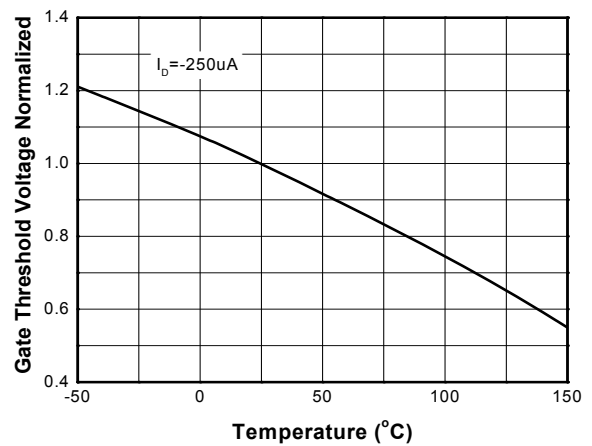
Thermal resistance ratings

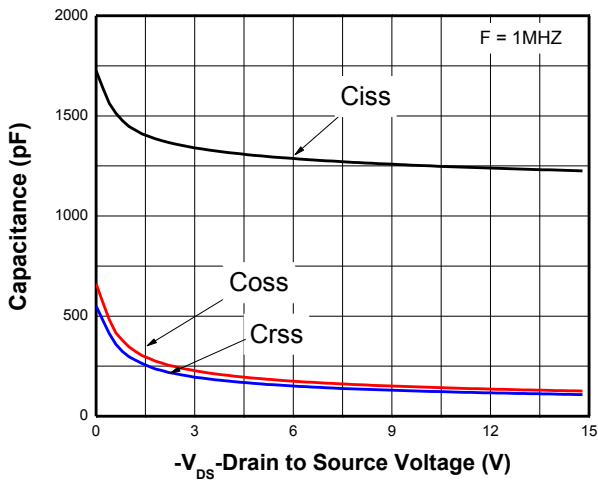
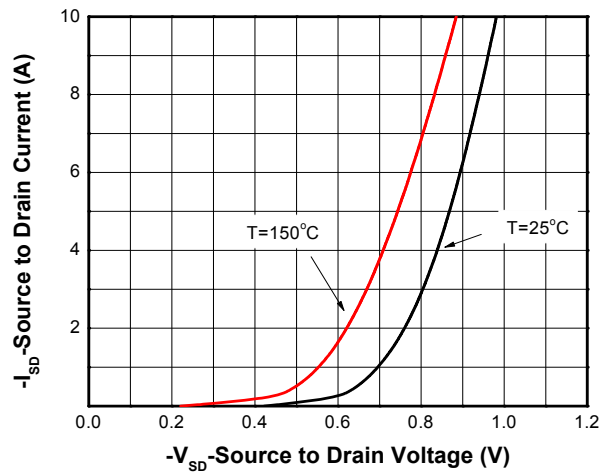
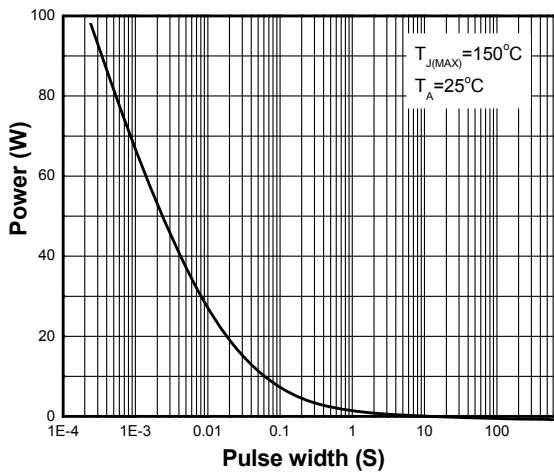
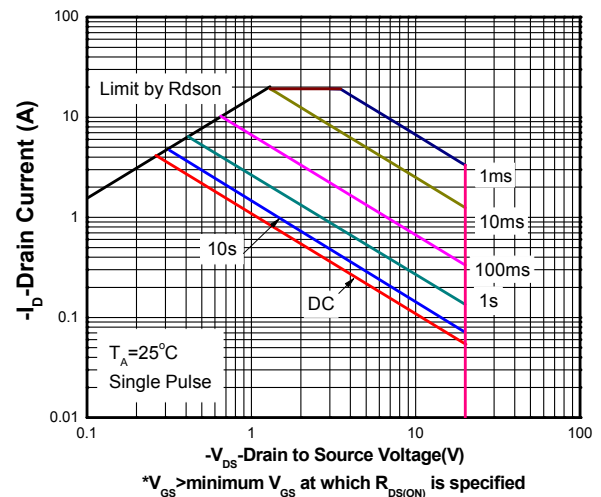
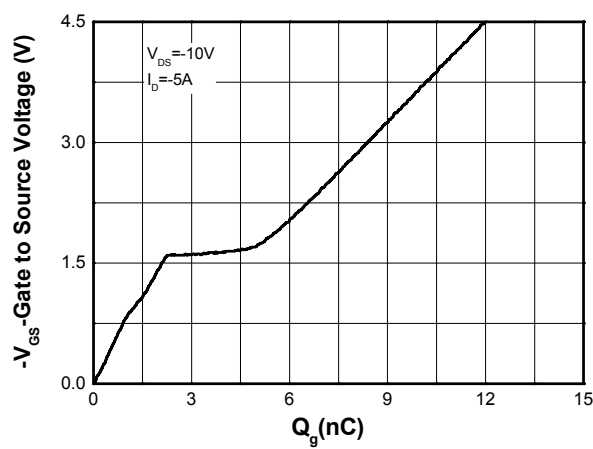
Single Operation					
Parameter		Symbol	Typical	Maximum	Unit
Junction-to-Ambient Thermal Resistance ^a	$t \leq 10 \text{ s}$	$R_{\theta JA}$	70	85	$^\circ\text{C/W}$
	Steady State		90	115	
Junction-to-Ambient Thermal Resistance ^b	$t \leq 10 \text{ s}$	$R_{\theta JA}$	95	110	
	Steady State		110	135	
Junction-to-Case Thermal Resistance	Steady State	$R_{\theta JC}$	40	60	

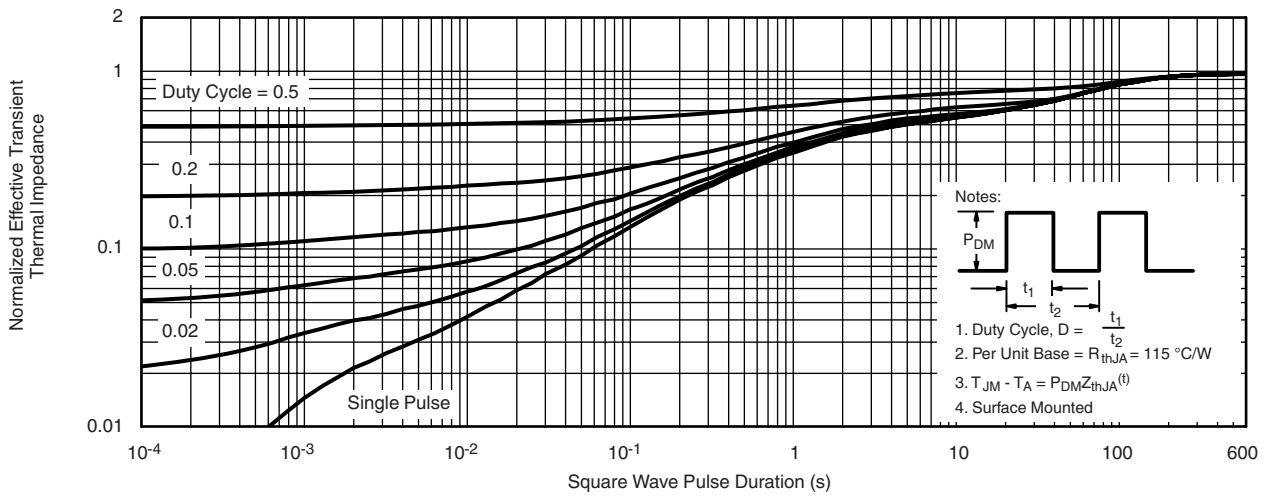
- a. Surface mounted on FR4 Board using 1 in sq pad size, 1oz Cu.
- b. Surface mounted on FR4 board using the minimum recommended pad size, 1oz Cu.
- c. Repetitive rating, pulse width limited by junction temperature, $t_p=10\mu\text{s}$, Duty Cycle=1%.
- d. Repetitive rating, pulse width limited by junction temperature $T_J(\text{MAX})=150^\circ\text{C}$.

Electronics Characteristics (Ta=25°C, unless otherwise noted)

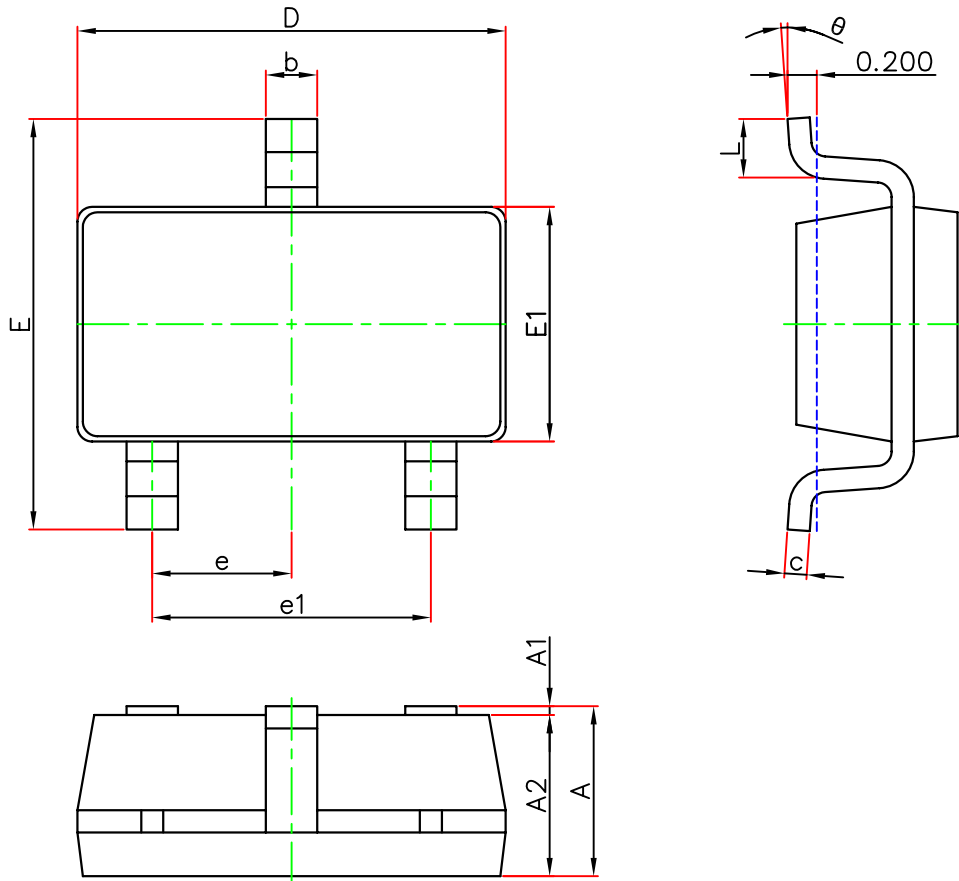
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Drain-to-Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0\text{ V}, I_D = -250\mu\text{A}$	-20			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -16\text{ V}, V_{GS} = 0\text{ V}$			-1	μA
Gate-to-source Leakage Current	I_{GSS}	$V_{DS} = 0\text{ V}, V_{GS} = \pm 12\text{ V}$			± 100	nA
ON CHARACTERISTICS						
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = -250\mu\text{A}$	-0.4	-0.7	-1.0	V
Drain-to-source On-resistance	$R_{DS(on)}$	$V_{GS} = -4.5\text{ V}, I_D = -4.9\text{ A}$		33	43	m Ω
		$V_{GS} = -2.5\text{ V}, I_D = -3.1\text{ A}$		44	58	
		$V_{GS} = -1.8\text{ V}, I_D = -2.0\text{ A}$		65	88	
Forward Transconductance	g_{FS}	$V_{DS} = -5\text{ V}, I_D = -3.0\text{ A}$		4	9	S
CHARGES, CAPACITANCES AND GATE RESISTANCE						
Input Capacitance	C_{ISS}	$V_{GS} = 0\text{ V}, f = 1.0\text{ MHz}, V_{DS} = -10\text{ V}$		1251		pF
Output Capacitance	C_{OSS}			145		
Reverse Transfer Capacitance	C_{RSS}			124		
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = -4.5\text{ V}, V_{DS} = -10\text{ V}, I_D = -5.0\text{ A}$		12		nC
Threshold Gate Charge	$Q_{G(TH)}$			0.85		
Gate-to-Source Charge	Q_{GS}			2.5		
Gate-to-Drain Charge	Q_{GD}			2.8		
SWITCHING CHARACTERISTICS						
Turn-On Delay Time	$t_d(ON)$	$V_{GS} = -10\text{ V}, V_{DS} = -15\text{ V}, I_D = -5\text{ A}, R_G = 6\Omega$		7.8		ns
Rise Time	t_r			6.4		
Turn-Off Delay Time	$t_d(OFF)$			80		
Fall Time	t_f			18		
BODY DIODE CHARACTERISTICS						
Forward Voltage	V_{SD}	$V_{GS} = 0\text{ V}, I_S = -1\text{ A}$	-0.5	-0.75	-1.1	V

Typical Characteristics (Ta=25°C, unless otherwise noted)

Output characteristics

Transfer characteristics

On-Resistance vs. Drain current

On-Resistance vs. Gate-to-source voltage

On-Resistance vs. Junction temperature

Threshold voltage vs. Temperature


Capacitance

Body diode forward voltage

Single pulse power

Safe operating power

Gate Charge Characteristics



Transient thermal response (Junction-to-Ambient)

Package outline dimensions
SOT-23-3L


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E1	1.500	1.700	0.059	0.067
E	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°